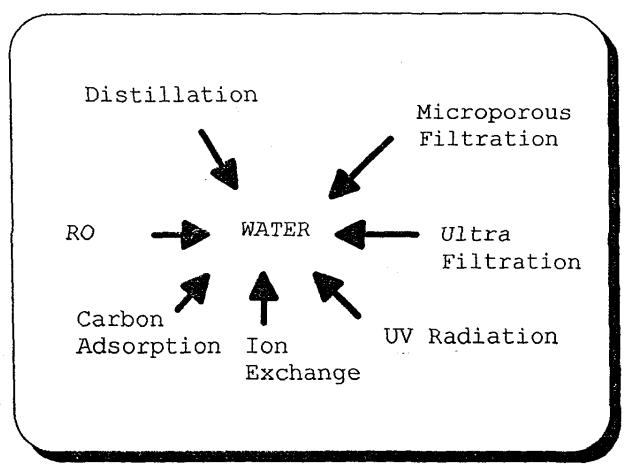
Water cleanness is a complex and costly process. City water contains unacceptable amounts of the following contaminants:

- Particulates (Silt, Colloids, Pipe debris)
- Dissolved Organics
- Dissolved Inorganics
- Micro-organism (Bacteria, Virus, Fungus)
- Pyrogen (Dead or Injured bacteria)

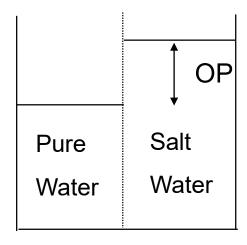


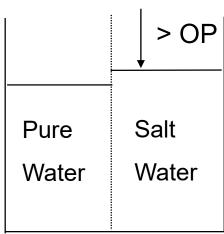
Technologies used to purify water



Filtration:

- Remove particulates.
- Nominal filters for pre-treatment.
- Absolute filters for post-treatment (0.22um).
- Micro-porous membrane filters removes even micro-organism but costly & not re-generable.
- Adsorption filters (Long Life) or Activated Carbon adsorption filter to trap dissolved organic but not particles, dissolved inorganic and bacteria, mainly to remove chlorine but bacteria build up in the line when Cl removed





Reverse Osmosis:

- Osmosis is movement of solvent from dilute solution to concentrated solution until equilibrium where an osmotic pressure (OP) exists.
- Reverse osmosis is applying pressure to overcome the osmotic pressure so that solvent will flow from concentrated solution to dilute solution through a membrane.
- Membranes: Cellulose acetate,
 Polysulfone & Polyamides.

Reverse Osmosis:

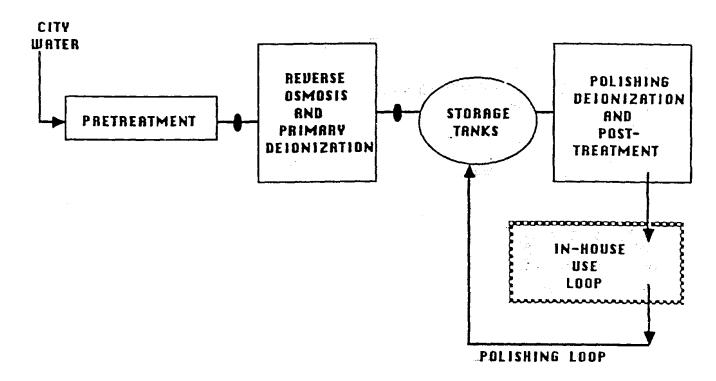
- % removal technology (not absolute) and Gases not removed.
- Removes Particles, Organic (large molecular weight easily removed), 99% Bacteria and Pyrogens.
- Polyvalent ions (99%), Monovalent ions (Sodium, 90%)
- Factors: Temperature, PH, Bacteria, Chlorine and Scaling Tendency of water
- Minimum maintenance

De-Ionization (DI):

- Removes dissolved inorganics/minerals, ionized salts by Ion Exchange with synthetic resin.
- Does not remove particles, pyrogens and bacteria instead can even generate particles and culture bacteria.
- Purity of water measured by specific resistance (>18M).
- Current technology includes
 Electrodeionization (EDI) & Capacitive
 Deionization (CDI).

UV Treatment:

- Eliminate trace organic: TOC (Total Organic Count) reduction.
- Post-Treatment or combine with DI to control bacteria or even better Point of Use.



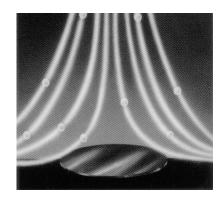
Typical conventional ultrahigh purity water treatment system.

A surface transfer of electrostatic charge between objects at different potentials caused by direct contact or induced by electrostatic field.

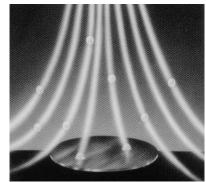
Type of ESD Failures:

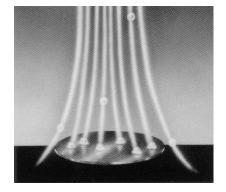
- Thermal (avalanche) breakdown
- Dielectric breakdown
- Metallization Melt

Another problem: Attraction of Particles by Charged Surface



Without static charge





Wafer charged to 500V Wafer charged to 4000V







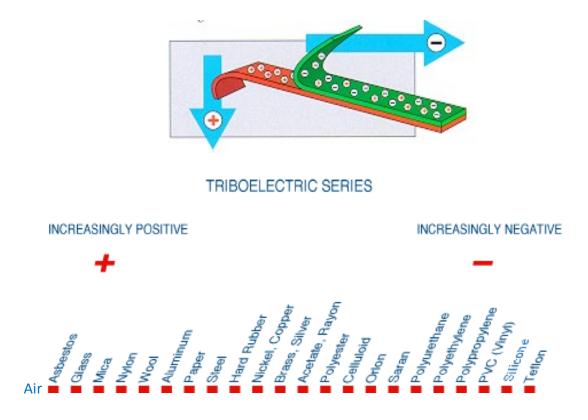
Proofs of ESD damage to IC

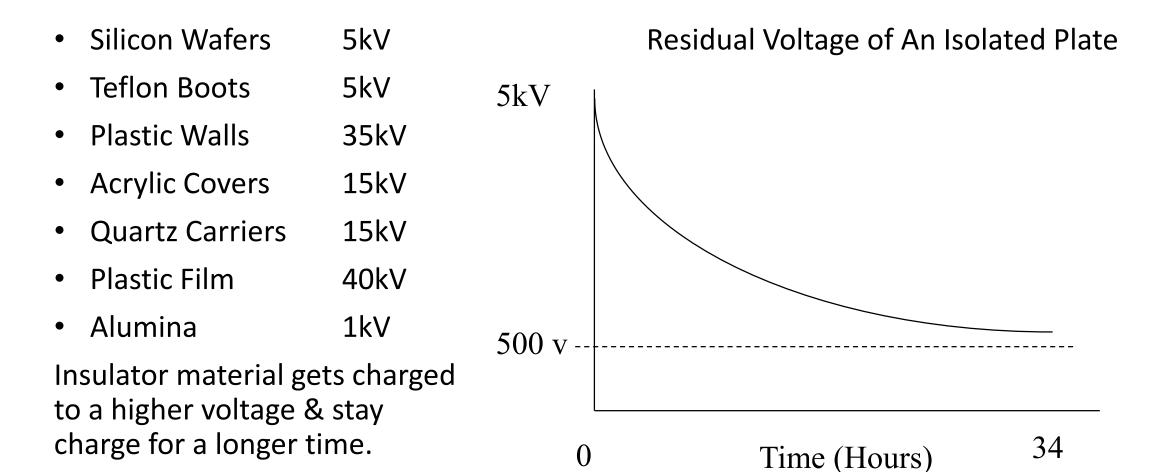
Presence of charge & therefore the voltage as a result of the electric field from the charged surface is caused by:

- Triboelectric charging
- Changes in capacitance
- Induction

Triboelectric Charging:

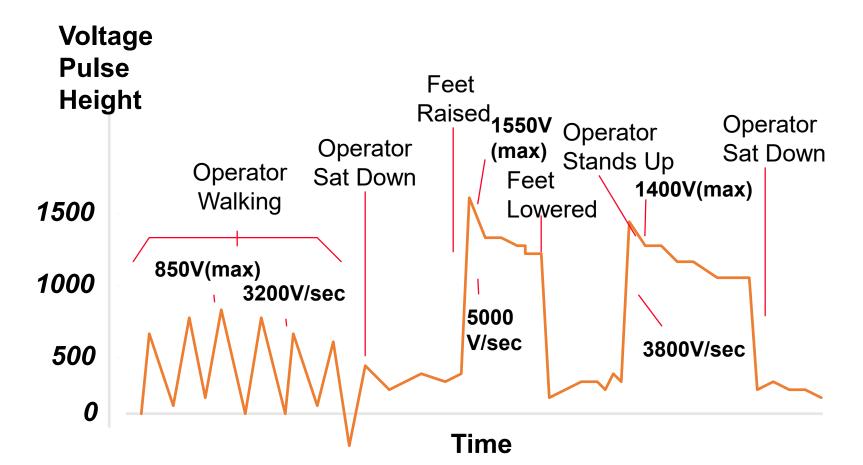
- The electrification of dissimilar materials through physical contact and separation, and the positive and negative charges so formed.
- Static Charge on contacting surfaces can be increased with addition of friction or rubbing.





Changes in Capacitance:

- Voltage on an object is greatly affected by the capacitance of the object.
- Capacitance can change in the environment due to position of the object relative to other objects in the area, for example human movements of sitting & standing.



Induction:

 Process of producing charges on a material through space at a distance by the influence of an electric field.

ESD Control through:

- Prevention:
 - ✓ ESD Safe material to reduce generation.
 - ✓ Humidity level 40% to 50% (Too dry ESD, Too humid Oxidation problems)
- Protection:
 - ✓ Education of personnel on movements that can create high voltages.
 - ✓ Faraday Cage shielding during storage and transport to protect against charging by Induction.
- Elimination:
 - ✓ Grounding for charge to migrate from conductive objects/human to ground.
 - ✓ Neutralization of charge on insulators and isolated conductive objects by Ionizers.

Insulator (109 ohms to infinity)

material that prevents or limits the flow of electrons

Conductive (0 to 10⁶ ohms)

material that allows electrons flow easily

Static Dissipative (10⁶ to 10⁹ ohms)

 material that behave in-between insulator and conductive, it permits electrons flow but at a slower rate than conductive material

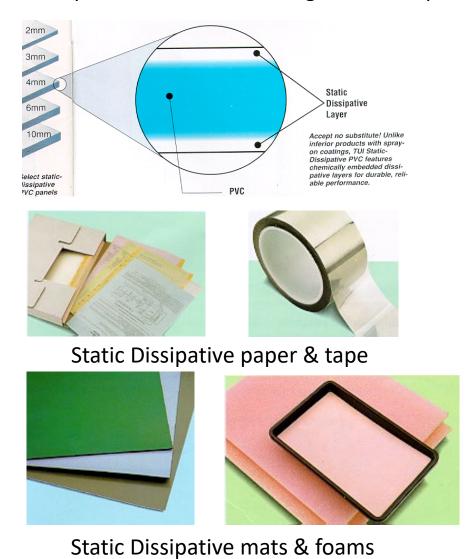
Antistatic material refers to the property of material that inhibits triboelectric charging & shall not triboelectric charge to greater than +/- 200 volts under normal/intended usage.

A material's antistatic property does not possessarily correlate to resistivity or resistance.

A material's antistatic property does not necessarily correlate to resistivity or resistance.

Static Dissipative materials are naturally Antistatic & is the material used to control ESD by reducing charge production & for the ease of elimination.

Examples of ESD Control using Static Dissipative materials at the surface:







Static Dissipative Bags





Static Dissipative cleanroom apparel, chair & raised floor

- Shielding is used to protect electrostatic susceptible items when they are being transported between Static Protected Areas.
- Shielding is a requirement for the most sensitive classes of components in Military contracts and many commercial specifications.
- A Static Shield can attenuate an electrostatic field & must be conductive (Faraday Cage).



Conductive Shielding Bags

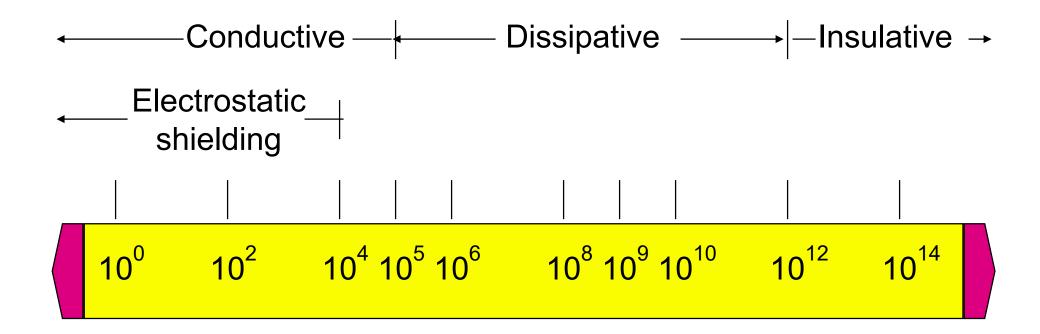
Construction of ESD Safe Bags:

	METAL-OUT BAGS	METAL-IN BAGS
	DY3816	DY3650 / DY3660
	Aluminium	Antistatic Polyester
	Polyester	Aluminium
	Antistatic Polyethylene	Antistatic Polyethylene

Multi Layer Conductive Shielding & Static Dissipative Bags possible



Conductive box for transport







Wrist straps & heel straps (non cleanroom) grounding to eliminate static charges.

- Grounding insulators neither removes nor prevents surface charges.
- There should not be any Insulator material used in the first place.
- But this is impossible, for example computer body or insulator on electrical wires.
- Ionizers are used.



Local area air ionizer



Ionizing air gun



Laminar flow workstation Ionizer